Amendments to the Claims:

The listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

1. (Currently amended) A system for acquiring semiconductor process status information, comprising:

an equipment server for sending a start command according to a first protocol;

a computer system server connected to the equipment server for converting the start command from the first protocol to a second protocol and outputting the converted start command;

a protocol converter connected to the computer system server for converting the start command from the second protocol to a third protocol and outputting the converted command according to the third protocol;

an AD/DA module connected to the protocol converter for converting the start command from the third protocol to an analog signal and outputting the converted command;

an external sensor connected to the AD/DA module for acquiring semiconductor ~~equipment~~ process status information as initiated by the start command;

wherein the AD/DA module converts the semiconductor process status information from ~~the~~ analog signals to the third protocol and outputs the converted information to the protocol converter; the protocol converter converts the semiconductor process status information from the third protocol to the second protocol and outputs the

converted information to the computer system server; and the computer system server outputs the converted information to the equipment server.

2. (original) The system as claimed in claim 1, wherein the status information comprises temperature, pressure, flow rate, consistency, rotational speed, voltage value, or electric current value.

3. (original) The system as claimed in claim 1, wherein standard voltage value input of the semiconductor process status information are ±15mV, ±50mV, ±100mV, ±150mV, ±500mV, ±1V, ±2.5V, ±5V or ±10V.

4. (Currently amended) The system, as claimed in claim 1, wherein standard current input of the semiconductor ~~equipment~~ process status information is 0~20mA or ±4~20mA.

5. (Currently amended) The system as claimed in claim 1, wherein standard direct sensor input of the semiconductor process ~~equipment~~ status information is from a thermocouple ~~(J, K, T, E, R, S, B type)~~ or a resistance temperature detector (RTD)~~RTD (Pt, Ni, Balco)~~.

6. (Currently amended) The system as claimed in claim 1, wherein standard digital input of the semiconductor process ~~equipment~~ status information is high or low ~~(0/1)~~.

7. (Currently amended) A system for acquiring semiconductor process status information, comprising:

an equipment server for outputting a start command according to a HSMS protocol;

a computer system server connected to the equipment server for converting the start command from the HSMS protocol to a RS232 protocol and outputting the converted command;

a protocol converter connected to the computer system server for converting the start command from the RS232 protocol to a RS485 protocol and outputting the converted command;

an AD/DA module connected to the protocol converter for converting the start command from the RS485 command to an analog signal and outputting the converted command;

an external sensor connected to the AD/DA module for acquiring semiconductor process ~~equipment~~ status information as initiated by the start command;

wherein the AD/DA module converts the semiconductor process status information from ~~the~~ analog signals to the RS485 protocol and outputs the converted information to the protocol converter; the protocol converter converts the semiconductor process status information from the RS485 protocol to the RS232 protocol and outputs the converted information to the computer system server; and the computer system server outputs the semiconductor process status information to the equipment server.

8. (original) The system as claimed in claim 7, wherein the status information comprises temperature, pressure, flow rate, consistency, rotational speed, voltage value, or electric current value.

9. (original) The system as claimed in claim 7, wherein standard voltage value input of the status information is ±15mV, ±50mV, ±100mV, ±150mV, ±500mV, ±1V, ±2.5V, ±5V or ±10V.

10. (Currently amended) The system, as claimed in claim 7, wherein standard current input of the semiconductor process ~~equipment~~ status information is ±0~20mA or ±4~20mA.

11. (Currently amended) The system as claimed in claim 7, wherein standard direct sensor input of the semiconductor process ~~equipment~~ status information is from a thermocouple ~~(J, K, T, E, R, S, B type)~~ or a resistance temperature detector (RTD)~~RTD (Pt, Ni, Balco)~~.

12. (Currently amended) The system as claimed in claim 7, wherein standard digital input of the semiconductor process~~equipment~~ status information is high or low ~~(0/1)~~.

13. (Currently amended) A method for acquiring semiconductor process status information, comprising the steps of:

a tool application program outputting a start command according to a ~~first~~ HSMS protocol;

converting the start command from the ~~first~~ HSMS protocol to a ~~second~~ RS232 protocol and outputting the converted start command;

converting the start command from the ~~second~~ RS232 protocol to a ~~third~~ RS485 protocol and outputting the converted command according to the RS485~~third~~ protocol;

converting the start command from the RS485~~third~~ protocol to an analog signal and outputting the converted command;

activation of an external sensor by the start command;

acquiring semiconductor process ~~equipment~~ status information from the external sensor;

converting the semiconductor process status information from analog signals to the RS485~~third~~ protocol and outputting the converted information according to the RS485~~third~~ protocol;

converting the semiconductor process status information from the RS485~~third~~ protocol to the RS232~~second~~ protocol and outputting the converted information according to the RS232~~second~~ protocol;

converting the semiconductor process status information from the RS232~~second~~ protocol to the ~~first~~ HSMS protocol; and

outputting the semiconductor process status information to an equipment server according to the HSMS~~first~~ server.

14. (cancelled)

15. (original) The method as claimed in claim 13, wherein the status information comprises temperature, pressure, flow rate, consistency, rotational speed, voltage value, or electric current value.

16. (original) The method as claimed in claim 13, wherein standard voltage value input of the status information is ±15mV, ±50mV, ±100mV, ±150mV, ±500mV, ±1V, ±2.5V, ±5V or ±10V.

17. (Currently amended) The method, as claimed in claim 13, wherein standard current input of the semiconductor process ~~equipment~~ status information is ±0~20mA or ±4~20mA.

18. (Currently amended) The method as claimed in claim 13, wherein standard direct sensor input of the semiconductor process ~~equipment~~ status information is from a thermocouple ~~(J, K, T, E, R, S, B type)~~ or a resistance temperature detector (RTD)~~RTD (Pt, Ni, Balco)~~.

19. (Currently amended) The method as claimed in claim 13, wherein standard digital input of the semiconductor process ~~equipment~~ status information is high or low ~~(0/1)~~.